Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.019”**

**.019”**

**Anode**

**Cathode**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .010”**

**Backside Potential: Cathode**

**Mask Ref: KDRW-0127**

**APPROVED BY: DK DIE SIZE .019” X .019” DATE: 11/9/21**

**MFG: KNOX / MICRO METRICS THICKNESS .007” P/N: 1N5238**

**DG 10.1.2**

#### Rev B, 7/19/02